

IN THE CLAIMS

Claim 1. (original): A thermosetting resin composition comprising an epoxy resin (Component (A)) which has a number average molecular weight of 800 to 35,000, an average functional group number of more than 2 per one molecule, and a functional group equivalent of 150 to 2,000 g/mol, and which may have a polybutadiene or hydrogenated polybutadiene skeleton, and a resin (Component (B)) which has a number average molecular weight of 800 to 35,000, an average functional group number of more than 2 per one molecule, and a functional group equivalent of 150 to 2,000 g/mol, which has one or more functional groups selected from amino group, carboxyl group, acid anhydride group, mercapto group, hydroxyl group, isocyanate group and hydrazide group, and no blocked carboxyl group, and which may have a polybutadiene or hydrogenated polybutadiene skeleton, wherein the ratio of the Component (B) to the Component (A) is from 0.5 to 2.0 in terms of the overall equivalent number of the functional group (s) of Component (B) capable of reacting with the epoxy group of the Component (A) to the overall equivalent number of the epoxy group of the Component (A).

Claim 2. (currently amended): A thermosetting resin composition wherein an epoxy resin (Component (c)) which has a number average molecular weight of 7,000 to 35,000, an average functional group number of 2 or more per one molecule, and a functional group equivalent of 2,000 to 18,000 g/mol, and which may have a polybutadiene or hydrogenated polybutadiene skeleton, is incorporated in combination with the Component (A) as set forth in Claim 1, both resins being incorporated in such ratio that the total average equivalent becomes 300 to 2,000 g/mol (both resins being collectively referred to herein as Component (C)), and a resin (Component (d)) which has a number average molecular weight of 7,000 to 35,000, an average functional group number of 2 or more per one molecule, and a functional group

equivalent of 2,000 to 18,000 g/mol, which has one or more functional groups selected from carboxyl group, amino group, acid anhydride group, hydrazide group, mercapto group, hydroxyl group and isocyanate group, and no blocked carboxyl group, and which may have a polybutadiene or hydrogenated polybutadiene skeleton, is incorporated in combination with the Component (B) as set forth in Claim 1, both resins being incorporated in such ratio that the total average equivalent becomes 300 to 2,000 g/mol (both resins being collectively referred to herein as Component (D)), and wherein the ratio of the Component (D) to the Component (C) is from 0.5 to 2.0 in terms of the overall equivalent number of the functional group (s) of Component (D) capable of reacting with the epoxy group of the Component(C) to the overall equivalent number of the epoxy group of the Component (C).

Claims 3-5 (cancelled)

Claim 6. (new): A thermosetting resin composition wherein the Component (A) as set forth in Claim 1, and a resin (Component (d)) which has a number average molecular weight of 7,000 to 35,000, an average functional group number of 2 or more per one molecule, and a functional group equivalent of 2,000 to 18,000 g/mol, which has one or more functional groups selected from carboxyl group, amino group, acid anhydride group, hydrazide group, mercapto group, hydroxyl group and isocyanate group, and no blocked carboxyl group, and which may have a polybutadiene or hydrogenated polybutadiene skeleton, is incorporated in combination with the Component (B) as set forth in Claim 1, both resins being incorporated in such ratio that the total average equivalent becomes 300 to 2,000 g/mol (both resins being collectively referred to herein as Component (D)), and wherein the ratio of the Component (D) to the Component (A) is from 0.5 to 2.0 in terms of the overall equivalent number of the

functional group(s) of Component (D) capable of reacting with the epoxy group of the Component (A) to the equivalent number of the epoxy group of the Component (A).

Claim 7. (new): A thermosetting resin composition wherein an epoxy resin (Component (c)) which has a number average molecular weight of 7,000 to 35,000, an average functional group number of 2 or more per one molecule, and a functional group equivalent of 2,000 to 18,000 g/mol, and which may have a polybutadiene or hydrogenated polybutadiene skeleton, is incorporated in combination with the Component (A) as set forth in Claim 1, both resins being incorporated in such ratio that the total average equivalent becomes 300 to 2,000 g/mol (both resins being collectively referred to herein as Component (C)) and the Component (B) as set forth in Claim 1, and wherein the ratio of the Component (B) to the Component (C) is from 0.5 to 2.0 in terms of the equivalent number of the functional group(s) of Component (B) capable of reacting with the epoxy group of the Component (C) to the overall equivalent number of the epoxy group of the Component (C).

Claim 8. (new): An overcoating agent for flexible circuit boards, wherein said thermosetting resin composition as in any one of Claims 1, 2, 6 or 7 is employed.

Claim 9. (new): A film carrier comprising an insulating film and a pattern formed thereon of metal thin film, with a part or all of the insulating film in the folded region having been removed, wherein the circuit pattern side except the joint region including the folded region, is coated with said overcoating agent of Claim 8 and cured.

Claim 10. (new): A film carrier device employing said film carrier of Claim 9.